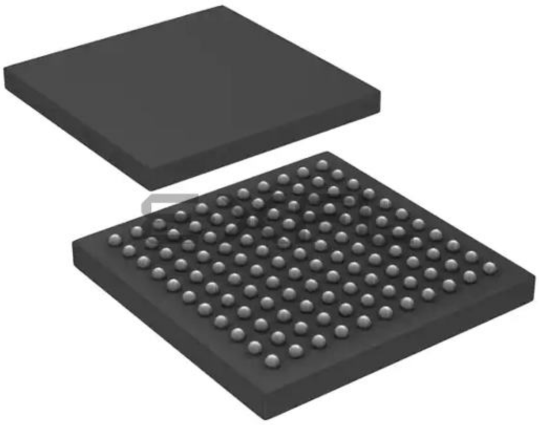
Microchip Technology - PIC32MX460F256LT-80V/BG Datasheet



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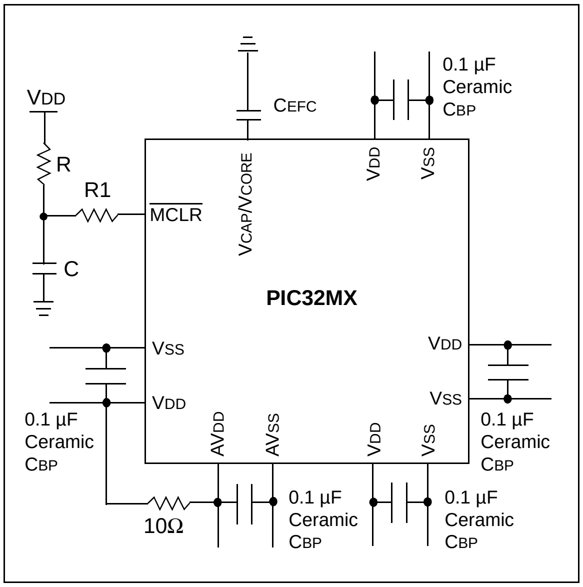
Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	MIPS32® M4K™
Core Size	32-Bit Single-Core
Speed	80MHz
Connectivity	I²C, IrDA, LINbus, PMP, SPI, UART/USART, USB OTG
Peripherals	Brown-out Detect/Reset, DMA, POR, PWM, WDT
Number of I/O	-
Program Memory Size	256KB (256K x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	32K x 8
Voltage - Supply (Vcc/Vdd)	2.3V ~ 3.6V
Data Converters	A/D 16x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	121-TFBGA
Supplier Device Package	121-TFBGA (10x10)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic32mx460f256lt-80v-bg

FIGURE 2-1: RECOMMENDED MINIMUM CONNECTION



2.2.1 BULK CAPACITORS

The use of a bulk capacitor is recommended to improve power supply stability. Typical values range from 4.7 µF to 47 µF. This capacitor should be located as close to the device as possible.

2.3 Capacitor on Internal Voltage Regulator (V_{CAP}/V_{CORE})

2.3.1 INTERNAL REGULATOR MODE

A low-ESR (< 1 Ohm) capacitor is required on the V_{CAP}/V_{CORE} pin, which is used to stabilize the internal voltage regulator output. The V_{CAP}/V_{CORE} pin must not be connected to V_{DD}, and must have a C_{EFC} capacitor, with at least a 6V rating, connected to ground. The type can be ceramic or tantalum. Refer to **Section 29.0 "Electrical Characteristics"** for additional information on C_{EFC} specifications. This mode is enabled by connecting the ENVREG pin to V_{DD}.

2.3.2 EXTERNAL REGULATOR MODE

In this mode the core voltage is supplied externally through the V_{CORE}/V_{CAP} pin. A low-ESR capacitor of 10 µF is recommended on the V_{CAP}/V_{CORE} pin. This mode is enabled by grounding the ENVREG pin.

The placement of this capacitor should be close to the V_{CAP}/V_{CORE}. It is recommended that the trace length not exceed one-quarter inch (6 mm). Refer to **Section 26.3 "On-Chip Voltage Regulator"** for details.

2.4 Master Clear ($\overline{MCLR}$) Pin

The $\overline{MCLR}$ pin provides for two specific device functions:

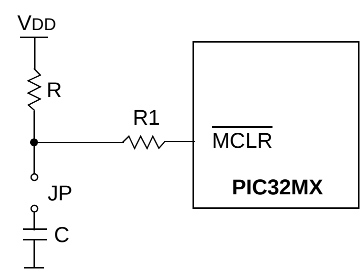
- Device Reset
- Device Programming and Debugging

Pulling The $\overline{MCLR}$ pin low generates a device reset. Figure 2-2 illustrates a typical MCLR circuit. During device programming and debugging, the resistance and capacitance that can be added to the pin must be considered. Device programmers and debuggers drive the $\overline{MCLR}$ pin. Consequently, specific voltage levels (V_{IH} and V_{IL}) and fast signal transitions must not be adversely affected. Therefore, specific values of R and C will need to be adjusted based on the application and PCB requirements.

For example, as illustrated in Figure 2-2, it is recommended that the capacitor C, be isolated from the $\overline{MCLR}$ pin during programming and debugging operations.

Place the components shown in Figure 2-2 within one-quarter inch (6 mm) from the $\overline{MCLR}$ pin.

FIGURE 2-2: EXAMPLE OF $\overline{MCLR}$ PIN CONNECTIONS



Note 1: R ≤ 10 kΩ is recommended. A suggested starting value is 10 kΩ. Ensure that the $\overline{MCLR}$ pin V_{IH} and V_{IL} specifications are met.

2: R1 ≤ 470Ω will limit any current flowing into $\overline{MCLR}$ from the external capacitor C, in the event of $\overline{MCLR}$ pin breakdown, due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS). Ensure that the $\overline{MCLR}$ pin V_{IH} and V_{IL} specifications are met.

3: The capacitor can be sized to prevent unintentional resets from brief glitches or to extend the device reset period during POR.

2.9 Configuration of Analog and Digital Pins During ICSP Operations

If MPLAB ICD 2, ICD 3 or REAL ICE is selected as a debugger, it automatically initializes all of the Analog-to-Digital input pins (ANx) as “digital” pins by setting all bits in the ADPCFG register.

The bits in this register that correspond to the Analog-to-Digital pins that are initialized by MPLAB ICD 2, ICD 3 or REAL ICE, must not be cleared by the user application firmware; otherwise, communication errors will result between the debugger and the device.

If your application needs to use certain Analog-to-Digital pins as analog input pins during the debug session, the user application must clear the corresponding bits in the ADPCFG register during initialization of the ADC module.

When MPLAB ICD 2, ICD 3 or REAL ICE is used as a programmer, the user application firmware must correctly configure the ADPCFG register. Automatic initialization of this register is only done during debugger operation. Failure to correctly configure the register(s) will result in all Analog-to-Digital pins being recognized as analog input pins, resulting in the port value being read as a logic ‘0’, which may affect user application functionality.

2.10 Unused I/Os

Unused I/O pins should not be allowed to float as inputs. They can be configured as outputs and driven to a logic-low state.

Alternately, inputs can be reserved by connecting the pin to VSS through a 1k to 10k resistor and configuring the pin as an input.

TABLE 4-4: INTERRUPT REGISTERS MAP FOR PIC32MX320F032H, PIC32MX320F064H, PIC32MX320F128H AND PIC32MX320F128L DEVICES ONLY[(1)]

Virtual Address (BF88_#)	Register Name	Bit Range	Bits 31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	All Resets
1000	INTCON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	SS0	0000
		15:0	—	—	—	MVEC	—	TPC<2:0>			—	—	—	INT4EP	INT3EP	INT2EP	INT1EP	INT0EP	0000
1010	INTSTAT[(2)]	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	SRIPL<2:0>			—	—	VEC<5:0>						0000
1020	IPTMR	31:16	IPTMR<31:0>																0000
		15:0																	0000
1030	IFS0	31:16	I2C1MIF	I2C1SIF	I2C1BIF	U1TXIF	U1RXIF	U1EIF	SPI1RXIF	SPI1TXIF	SPI1EIF	OC5IF	IC5IF	T5IF	INT4IF	OC4IF	IC4IF	T4IF	0000
		15:0	INT3IF	OC3IF	IC3IF	T3IF	INT2IF	OC2IF	IC2IF	T2IF	INT1IF	OC1IF	IC1IF	T1IF	INT0IF	CS1IF	CS0IF	CTIF	0000
1040	IFS1	31:16	—	—	—	—	—	—	—	FCEIF	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIF	FSCMIF	I2C2MIF	I2C2SIF	I2C2BIF	U2TXIF	U2RXIF	U2EIF	SPI2RXIF	SPI2TXIF	SPI2EIF	CMP2IF	CMP1IF	PMPIF	AD1IF	CNIF	0000
1060	IEC0	31:16	I2C1MIE	I2C1SIE	I2C1BIE	U1TXIE	U1RXIE	U1EIE	SPI1RXIE	SPI1TXIE	SPI1EIE	OC5IE	IC5IE	T5IE	INT4IE	OC4IE	IC4IE	T4IE	0000
		15:0	INT3IE	OC3IE	IC3IE	T3IE	INT2IE	OC2IE	IC2IE	T2IE	INT1IE	OC1IE	IC1IE	T1IE	INT0IE	CS1IE	CS0IE	CTIE	0000
1070	IEC1	31:16	—	—	—	—	—	—	—	FCEIE	—	—	—	—	—	—	—	—	0000
		15:0	RTCCIE	FSCMIE	I2C2MIE	—	—	—	—	—	SPI2RXIE	SPI2TXIE	SPI2EIE	CMP2IE	CMP1IE	PMPIE	AD1IE	CNIE	0000
1090	IPC0	31:16	—	—	—	INT0IP<2:0>			INT0IS<1:0>		—	—	—	CS1IP<2:0>			CS1IS<1:0>		0000
		15:0	—	—	—	CS0IP<2:0>			CS0IS<1:0>		—	—	—	CTIP<2:0>			CTIS<1:0>		0000
10A0	IPC1	31:16	—	—	—	INT1IP<2:0>			INT1IS<1:0>		—	—	—	OC1IP<2:0>			OC1IS<1:0>		0000
		15:0	—	—	—	IC1IP<2:0>			IC1IS<1:0>		—	—	—	T1IP<2:0>			T1IS<1:0>		0000
10B0	IPC2	31:16	—	—	—	INT2IP<2:0>			INT2IS<1:0>		—	—	—	OC2IP<2:0>			OC2IS<1:0>		0000
		15:0	—	—	—	IC2IP<2:0>			IC2IS<1:0>		—	—	—	T2IP<2:0>			T2IS<1:0>		0000
10C0	IPC3	31:16	—	—	—	INT3IP<2:0>			INT3IS<1:0>		—	—	—	OC3IP<2:0>			OC3IS<1:0>		0000
		15:0	—	—	—	IC3IP<2:0>			IC3IS<1:0>		—	—	—	T3IP<2:0>			T3IS<1:0>		0000
10D0	IPC4	31:16	—	—	—	INT4IP<2:0>			INT4IS<1:0>		—	—	—	OC4IP<2:0>			OC4IS<1:0>		0000
		15:0	—	—	—	IC4IP<2:0>			IC4IS<1:0>		—	—	—	T4IP<2:0>			T4IS<1:0>		0000
10E0	IPC5	31:16	—	—	—	SPI1IP<2:0>			SPI1IS<1:0>		—	—	—	OC5IP<2:0>			OC5IS<1:0>		0000
		15:0	—	—	—	IC5IP<2:0>			IC5IS<1:0>		—	—	—	T5IP<2:0>			T5IS<1:0>		0000
10F0	IPC6	31:16	—	—	—	AD1IP<2:0>			AD1IS<1:0>		—	—	—	CNIP<2:0>			CNIS<1:0>		0000
		15:0	—	—	—	I2C1IP<2:0>			I2C1IS<1:0>		—	—	—	U1IP<2:0>			U1IS<1:0>		0000
1100	IPC7	31:16	—	—	—	SPI2IP<2:0>			SPI2IS<1:0>		—	—	—	CMP2IP<2:0>			CMP2IS<1:0>		0000
		15:0	—	—	—	CMP1IP<2:0>			CMP1IS<1:0>		—	—	—	PMPIP<2:0>			PMPIS<1:0>		0000
1110	IPC8	31:16	—	—	—	RTCCIP<2:0>			RTCCIS<1:0>		—	—	—	FSCMIP<2:0>			FSCMIS<1:0>		0000
		15:0	—	—	—	I2C2IP<2:0>			I2C2IS<1:0>		—	—	—	U2IP<2:0>			U2IS<1:0>		0000
1140	IPC11	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	—	—	—	—	—	—	—	—	—	—	—	FCEIP<2:0>			FCEIS<1:0>		0000

Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: Except where noted, all registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

2: This register does not have associated CLR, SET, and INV registers.

TABLE 4-9: OUTPUT COMPARE1-5 REGISTERS MAP[(1)]

Virtual Address (BF80_#)	Register Name	Bit Range	Bits																All Resets
			31/15	30/14	29/13	28/12	27/11	26/10	25/9	24/8	23/7	22/6	21/5	20/4	19/3	18/2	17/1	16/0	
3000	OC1CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3010	OC1R	31:16	OC1R<31:0>																xxxx
		15:0																	xxxx
3020	OC1RS	31:16	OC1RS<31:0>																xxxx
		15:0																	xxxx
3200	OC2CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3210	OC2R	31:16	OC2R<31:0>																xxxx
		15:0																	xxxx
3220	OC2RS	31:16	OC2RS<31:0>																xxxx
		15:0																	xxxx
3400	OC3CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3410	OC3R	31:16	OC3R<31:0>																xxxx
		15:0																	xxxx
3420	OC3RS	31:16	OC3RS<31:0>																xxxx
		15:0																	xxxx
3600	OC4CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3610	OC4R	31:16	OC4R<31:0>																xxxx
		15:0																	xxxx
3620	OC4RS	31:16	OC4RS<31:0>																xxxx
		15:0																	xxxx
3800	OC5CON	31:16	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	—	0000
		15:0	ON	—	SIDL	—	—	—	—	—	—	—	OC32	OCFLT	OCTSEL	OCM<2:0>			0000
3810	OC5R	31:16	OC5R<31:0>																xxxx
		15:0																	xxxx
3820	OC5RS	31:16	OC5RS<31:0>																xxxx
		15:0																	xxxx

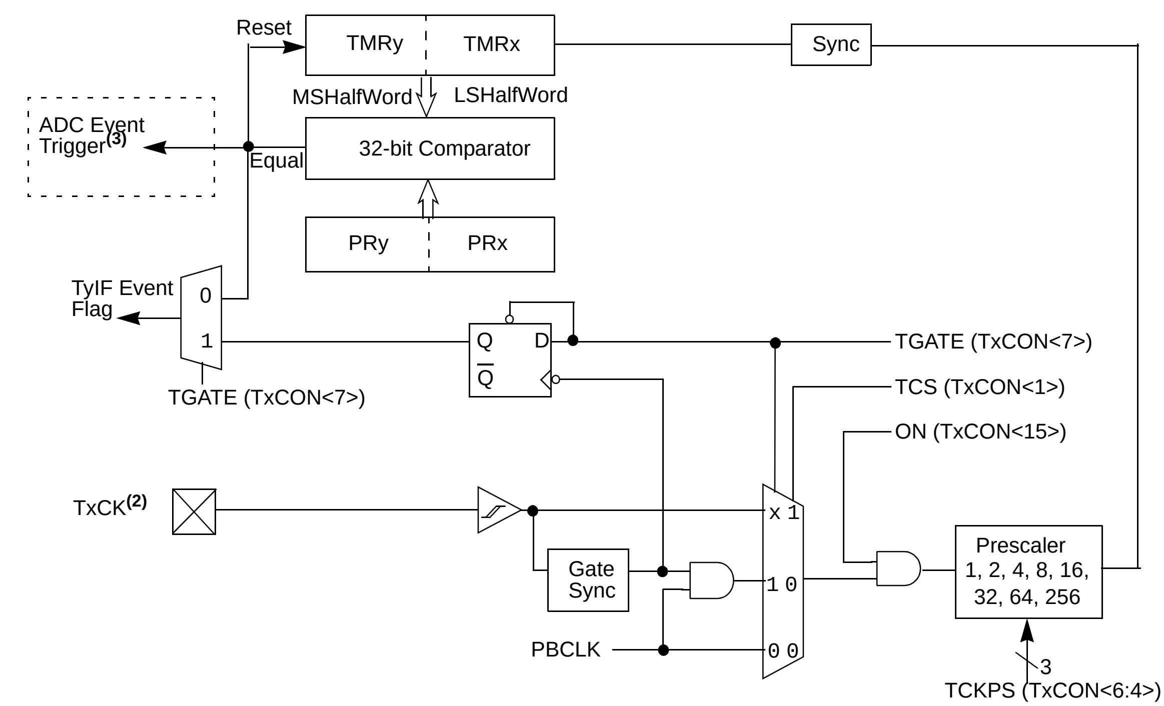
Legend: x = unknown value on Reset, — = unimplemented, read as '0'. Reset values are shown in hexadecimal.

Note 1: All registers in this table have corresponding CLR, SET and INV registers at their virtual addresses, plus offsets of 0x4, 0x8 and 0xC, respectively. See **Section 12.1.1 "CLR, SET and INV Registers"** for more information.

NOTES:

NOTES:

FIGURE 14-2: TIMER2/3, 4/5 BLOCK DIAGRAM (32-BIT)



Note 1: In this diagram, the use of 'x' in registers TxCON, TMRx, PRx and TxCK refers to either Timer2 or Timer4; the use of 'y' in registers TyCON, TMRy, PRy and TyIF refers to either Timer3 or Timer5.

2: TxCK pins are not available on 64-pin devices.

3: ADC event trigger is available only on Timer2/3 pair.

21.0 REAL-TIME CLOCK AND CALENDAR (RTCC)

> **Note 1:** This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. To complement the information in this data sheet, refer to **Section 29. "Real-Time Clock and Calendar (RTCC)"** (DS61125) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).
>
> **2:** Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

The PIC32MX RTCC module is intended for applications in which accurate time must be maintained for extended periods of time with minimal or no CPU intervention. Low-power optimization provides extended battery lifetime while keeping track of time.

The following are some of the key features of this module:

- Time: Hours, Minutes and Seconds
- 24-Hour Format (Military Time)
- Visibility of One-Half-Second Period
- Provides Calendar: Weekday, Date, Month and Year
- Alarm Intervals are configurable for Half of a Second, One Second, 10 Seconds, One Minute, 10 Minutes, One Hour, One Day, One Week, One Month and One Year
- Alarm Repeat with Decrementing Counter
- Alarm with Indefinite Repeat: Chime
- Year Range: 2000 to 2099
- Leap Year Correction
- BCD Format for Smaller Firmware Overhead
- Optimized for Long-Term Battery Operation
- Fractional Second Synchronization
- User Calibration of the Clock Crystal Frequency with Auto-Adjust
- Calibration Range: ±0.66 Seconds Error per Month
- Calibrates up to 260 ppm of Crystal Error
- Requirements: External 32.768 kHz Clock Crystal
- Alarm Pulse or Seconds Clock Output on RTCC pin

FIGURE 21-1: RTCC BLOCK DIAGRAM

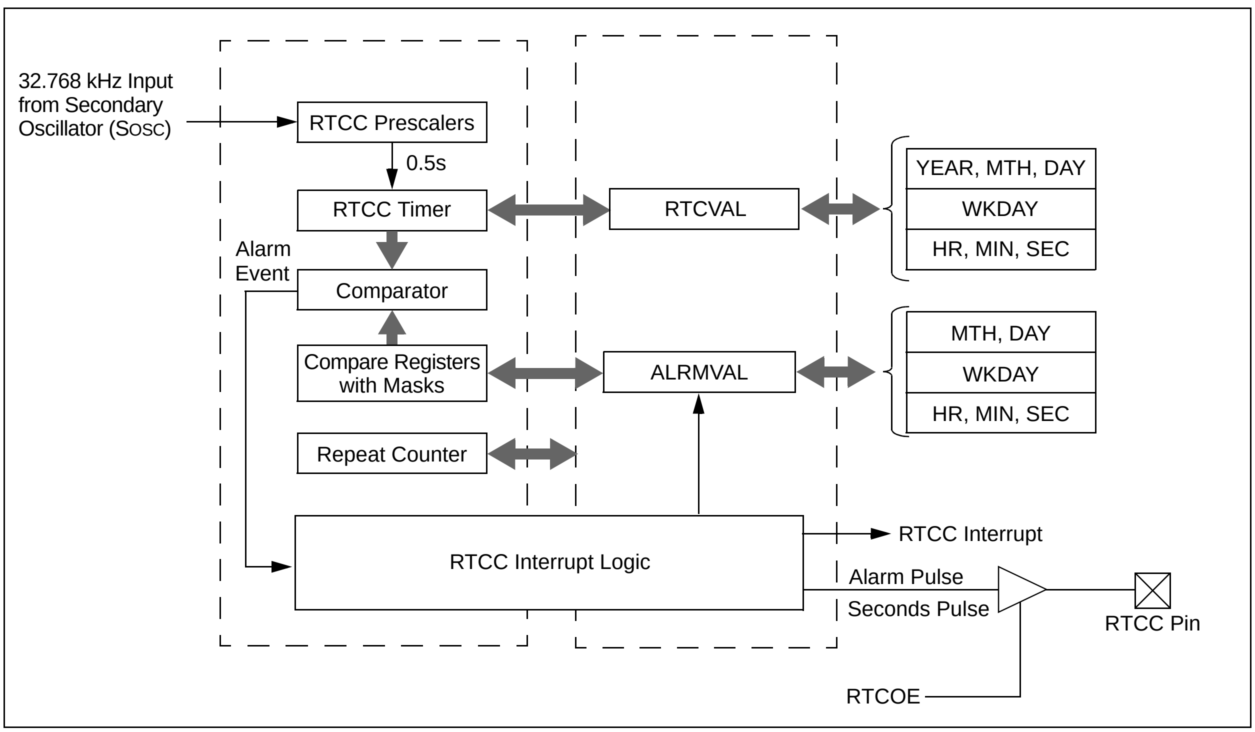
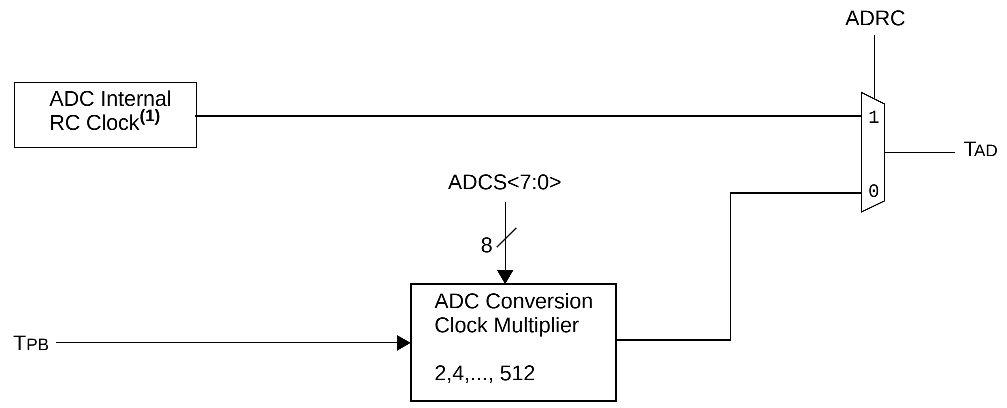


FIGURE 22-2: ADC CONVERSION CLOCK PERIOD BLOCK DIAGRAM



Note 1: See the ADC electrical characteristics for the exact RC clock value.

24.0 COMPARATOR VOLTAGE REFERENCE (CVREF)

Note 1:	This data sheet summarizes the features of the PIC32MX3XX/4XX family of devices. It is not intended to be a comprehensive reference source. Refer to **Section 20. "Comparator Voltage Reference (CVREF)"** (DS61109) of the *"PIC32 Family Reference Manual"*, which is available from the Microchip web site (www.microchip.com/PIC32).
2:	Some registers and associated bits described in this section may not be available on all devices. Refer to **Section 4.0 "Memory Organization"** in this data sheet for device-specific register and bit information.

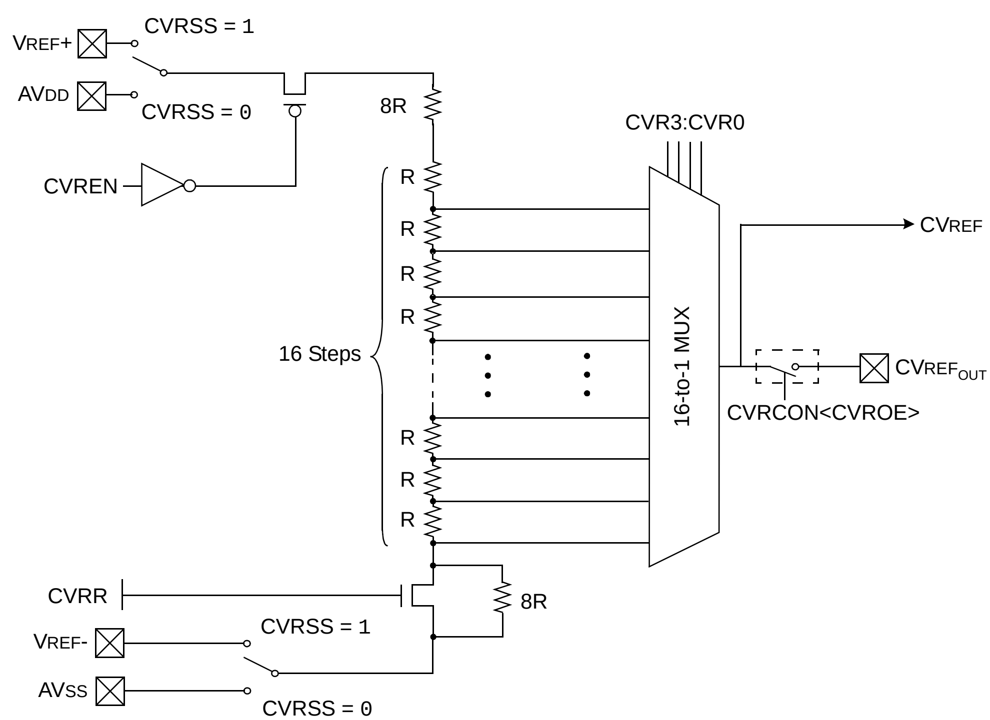
The CVREF is a 16-tap, resistor ladder network that provides a selectable reference voltage. Although its primary purpose is to provide a reference for the analog comparators, it also may be used independently of them.

A block diagram of the module is illustrated in Figure 24-1. The resistor ladder is segmented to provide two ranges of voltage reference values and has a power-down function to conserve power when the reference is not being used. The module's supply reference can be provided from either device VDD/VSS or an external voltage reference. The CVREF output is available for the comparators and typically available for pin output.

The comparator voltage reference has the following features:

- High and low range selection
- Sixteen output levels available for each range
- Internally connected to comparators to conserve device pins
- Output can be connected to a pin

FIGURE 24-1: COMPARATOR VOLTAGE REFERENCE BLOCK DIAGRAM



26.2 Watchdog Timer (WDT)

This section describes the operation of the WDT and Power-Up Timer of the PIC32MX3XX/4XX.

The WDT, when enabled, operates from the internal Low-Power Oscillator (LPRC) clock source and can be used to detect system software malfunctions by resetting the device if the WDT is not cleared periodically in software. Various WDT time-out periods can be selected using the WDT postscaler. The WDT can also be used to wake the device from Sleep or Idle mode.

The following are some of the key features of the WDT module:

- Configuration or software controlled
- User-configurable time-out period
- Can wake the device from Sleep or Idle

FIGURE 26-1: WATCHDOG AND POWER-UP TIMER BLOCK DIAGRAM

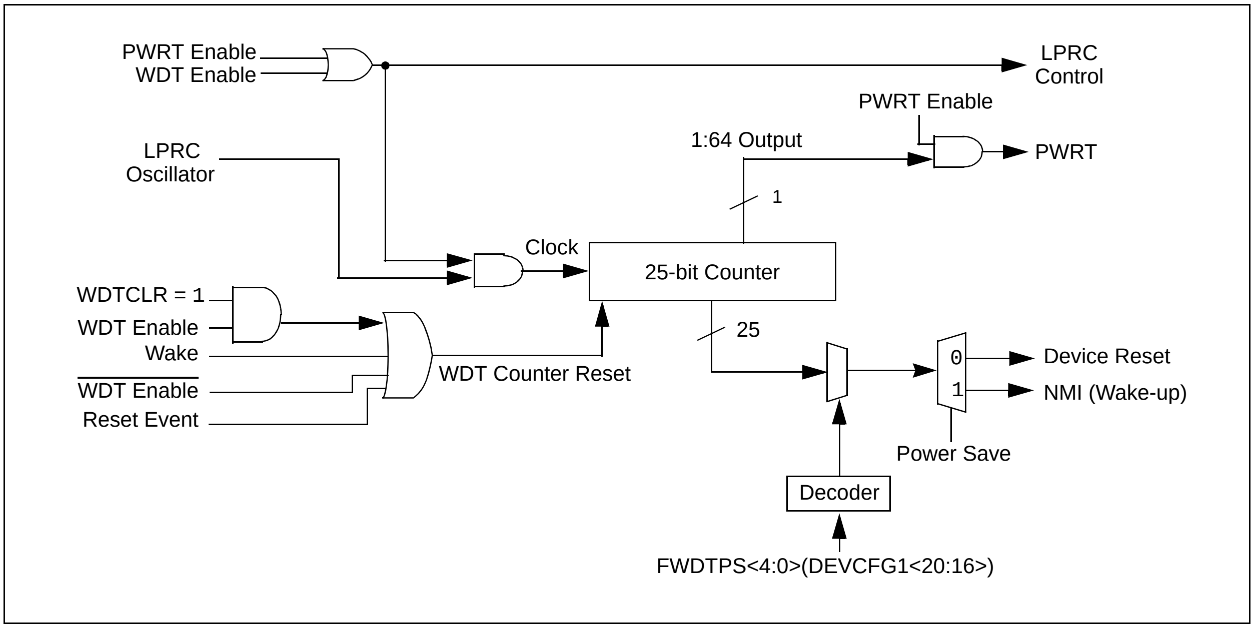


TABLE 27-1: MIPS32® INSTRUCTION SET (CONTINUED)

<table>
<tr><th>Instruction</th><th>Description</th><th>Function</th></tr>
<tr><td>BLEZL</td><td>Branch on Less Than or Equal to Zero Likely[1]</td><td>if Rs[31] || Rs == 0
  PC += (int)offset
else
  Ignore Next Instruction</td></tr>
<tr><td>BLTZ</td><td>Branch on Less Than Zero</td><td>if Rs[31]
  PC += (int)offset</td></tr>
<tr><td>BLTZAL</td><td>Branch on Less Than Zero and Link</td><td>GPR[31] = PC + 8
if Rs[31]
  PC += (int)offset</td></tr>
<tr><td>BLTZALL</td><td>Branch on Less Than Zero and Link Likely[1]</td><td>GPR[31] = PC + 8
if Rs[31]
  PC += (int)offset
else
  Ignore Next Instruction</td></tr>
<tr><td>BLTZL</td><td>Branch on Less Than Zero Likely[1]</td><td>if Rs[31]
  PC += (int)offset
else
  Ignore Next Instruction</td></tr>
<tr><td>BNE</td><td>Branch on Not Equal</td><td>if Rs != Rt
  PC += (int)offset</td></tr>
<tr><td>BNEL</td><td>Branch on Not Equal Likely[1]</td><td>if Rs != Rt
  PC += (int)offset
else
  Ignore Next Instruction</td></tr>
<tr><td>BREAK</td><td>Breakpoint</td><td>Break Exception</td></tr>
<tr><td>CLO</td><td>Count Leading Ones</td><td>Rd = NumLeadingOnes(Rs)</td></tr>
<tr><td>CLZ</td><td>Count Leading Zeroes</td><td>Rd = NumLeadingZeroes(Rs)</td></tr>
<tr><td>DERET</td><td>Return from Debug Exception</td><td>PC = DEPC
Exit Debug Mode</td></tr>
<tr><td>DI</td><td>Atomically Disable Interrupts</td><td>Rt = Status; $Status_{IE}$ = 0</td></tr>
<tr><td>DIV</td><td>Divide</td><td>LO = (int)Rs / (int)Rt
HI = (int)Rs % (int)Rt</td></tr>
<tr><td>DIVU</td><td>Unsigned Divide</td><td>LO = (uns)Rs / (uns)Rt
HI = (uns)Rs % (uns)Rt</td></tr>
<tr><td>EHB</td><td>Execution Hazard Barrier</td><td>Stop instruction execution until execution hazards are cleared</td></tr>
<tr><td>EI</td><td>Atomically Enable Interrupts</td><td>Rt = Status; $Status_{IE}$ = 1</td></tr>
<tr><td>ERET</td><td>Return from Exception</td><td>if $Status_{ERL}$
  PC = ErrorEPC
else
  PC = EPC
  $Status_{EXL}$ = 0
$Status_{ERL}$ = 0
LL = 0</td></tr>
<tr><td>EXT</td><td>Extract Bit Field</td><td>Rt = ExtractField(Rs, pos, size)</td></tr>
<tr><td>INS</td><td>Insert Bit Field</td><td>Rt = InsertField(Rs, Rt, pos, size)</td></tr>
<tr><td>J</td><td>Unconditional Jump</td><td>PC = PC[31:28] || offset<<2</td></tr>
</table>

Note 1: This instruction is deprecated and should not be used.

NOTES:

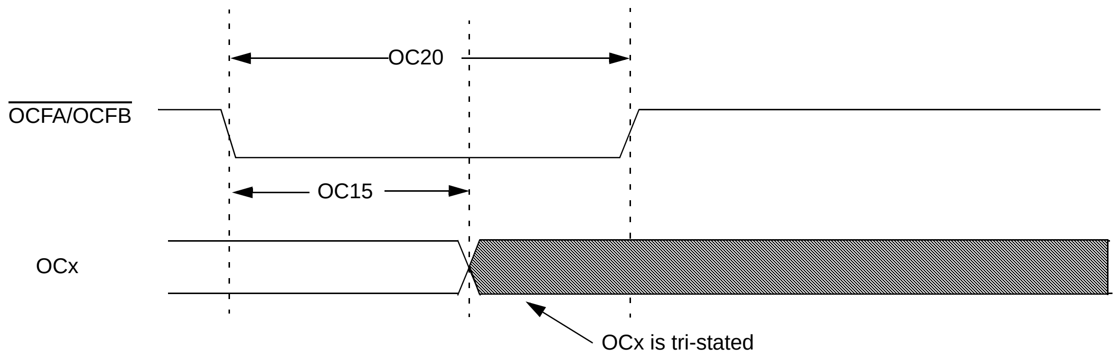
TABLE 29-9: DC CHARACTERISTICS: I/O PIN OUTPUT SPECIFICATIONS

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
	V_{OL}	**Output Low Voltage**					
DO10		I/O Ports	—	—	0.4	V	I_{OL} = 7 mA, V_{DD} = 3.6V
			—	—	0.4	V	I_{OL} = 6 mA, V_{DD} = 2.3V
DO16		OSC2/CLKO	—	—	0.4	V	I_{OL} = 3.5 mA, V_{DD} = 3.6V
			—	—	0.4	V	I_{OL} = 2.5 mA, V_{DD} = 2.3V
	V_{OH}	**Output High Voltage**					
DO20		I/O Ports	2.4	—	—	V	I_{OH} = -12 mA, V_{DD} = 3.6V
			1.4	—	—	V	I_{OH} = -12 mA, V_{DD} = 2.3V
DO26		OSC2/CLKO	2.4	—	—	V	I_{OH} = -12 mA, V_{DD} = 3.6V
			1.4	—	—	V	I_{OH} = -12 mA, V_{DD} = 2.3V

TABLE 29-10: ELECTRICAL CHARACTERISTICS: BROWN-OUT RESET (BOR)

DC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
BO10	V_{BOR}	BOR Event on V_{DD} transition high-to-low	2.0	—	2.3	V	—

FIGURE 29-9: OC/PWM MODULE TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

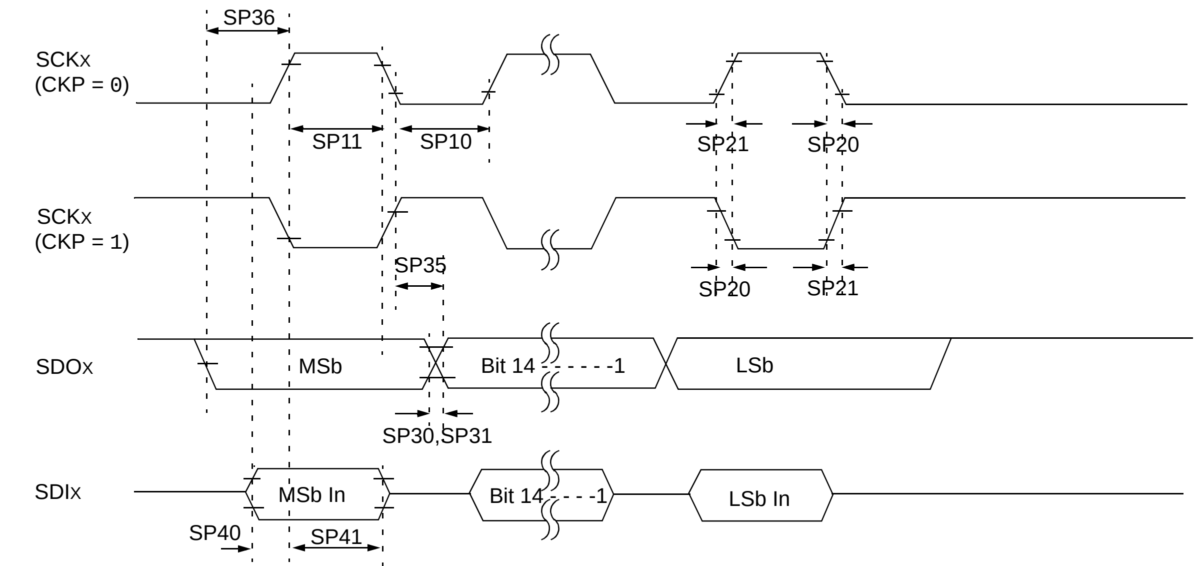
TABLE 29-27: SIMPLE OC/PWM MODE TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤ T_A ≤ +85°C for Industrial -40°C ≤ T_A ≤ +105°C for V-Temp				
Param No.	**Symbol**	**Characteristics(1)**	**Min**	**Typical(2)**	**Max**	**Units**	**Conditions**
OC15	T_{FD}	Fault Input to PWM I/O Change	—	—	25	ns	—
OC20	T_{FLT}	Fault Input Pulse Width	50	—	—	ns	—

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

FIGURE 29-11: SPIx MODULE MASTER MODE (CKE = 1) TIMING CHARACTERISTICS



Note: Refer to Figure 29-1 for load conditions.

TABLE 29-29: SPIx MODULE MASTER MODE (CKE = 1) TIMING REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤TA ≤+85°C for Industrial; -40°C ≤TA ≤+105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical(2)**	**Max.**	**Units**	**Conditions**
SP10	TSCL	SCKx Output Low Time(3)	TSCK/2	—	—	ns	—
SP11	TSCH	SCKx Output High Time(3)	TSCK/2	—	—	ns	—
SP20	TSCF	SCKx Output Fall Time(4)	—	—	—	ns	See parameter DO32
SP21	TSCR	SCKx Output Rise Time(4)	—	—	—	ns	See parameter DO31
SP30	TDOF	SDOx Data Output Fall Time(4)	—	—	—	ns	See parameter DO32
SP31	TDOR	SDOx Data Output Rise Time(4)	—	—	—	ns	See parameter DO31
SP35	TSCH2DOV, TSCL2DOV	SDOx Data Output Valid after SCKx Edge	—	—	15	ns	VDD > 2.7V
			—	—	20	ns	VDD < 2.7V
SP36	TDOV2SC, TDOV2SCL	SDOx Data Output Setup to First SCKx Edge	15	—	—	ns	—
SP40	TDIV2SCH, TDIV2SCL	Setup Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V
SP41	TSCH2DIL, TSCL2DIL	Hold Time of SDIx Data Input to SCKx Edge	15	—	—	ns	VDD > 2.7V
			20	—	—	ns	VDD < 2.7V

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Data in “Typical” column is at 3.3V, 25°C unless otherwise stated. Parameters are for design guidance only and are not tested.

3: The minimum clock period for SCKx is 40 ns. Therefore, the clock generated in Master mode must not violate this specification.

4: Assumes 50 pF load on all SPIx pins.

TABLE 29-36: ANALOG-TO-DIGITAL CONVERSION TIMING REQUIREMENTS

AC CHARACTERISTICS			Standard Operating Conditions: 2.3V to 3.6V (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics**	**Min.**	**Typical[1]**	**Max.**	**Units**	**Conditions**
Clock Parameters							
AD50	TAD	Analog-to-Digital Clock Period	65	—	—	ns	See Table 29-35 and **Note 2**
AD51	TRC	Analog-to-Digital Internal RC Oscillator Period	—	250	—	ns	See **Note 3**
Conversion Rate							
AD55	TCONV	Conversion Time	—	12 TAD	—	—	—
AD56	FCNV	Throughput Rate (Sampling Speed)	—	—	1000	KSPS	AVDD = 3.0V to 3.6V
			—	—	400	KSPS	AVDD = 2.5V to 3.6V
AD57	TSAMP	Sample Time	1 TAD	—	—	—	TSAMP must be ≥ 132 ns.
Timing Parameters							
AD60	TPCS	Conversion Start from Sample Trigger	—	1.0 TAD	—	—	Auto-Convert Trigger (SSRC<2:0> = 111) not selected. See **Note 3**
AD61	TPSS	Sample Start from Setting Sample (SAMP) bit	0.5 TAD	—	1.5 TAD	—	—
AD62	TCSS	Conversion Completion to Sample Start (ASAM = 1)	—	0.5 TAD	—	—	See **Note 3**
AD63	TDPU	Time to Stabilize Analog Stage from Analog-to-Digital OFF to Analog-to-Digital ON	—	—	2	µs	See **Note 3**

Note 1: These parameters are characterized, but not tested in manufacturing.

2: Because the sample caps will eventually lose charge, clock rates below 10 kHz can affect linearity performance, especially at elevated temperatures.

3: Characterized by design but not tested.

FIGURE 29-20: PARALLEL SLAVE PORT TIMING

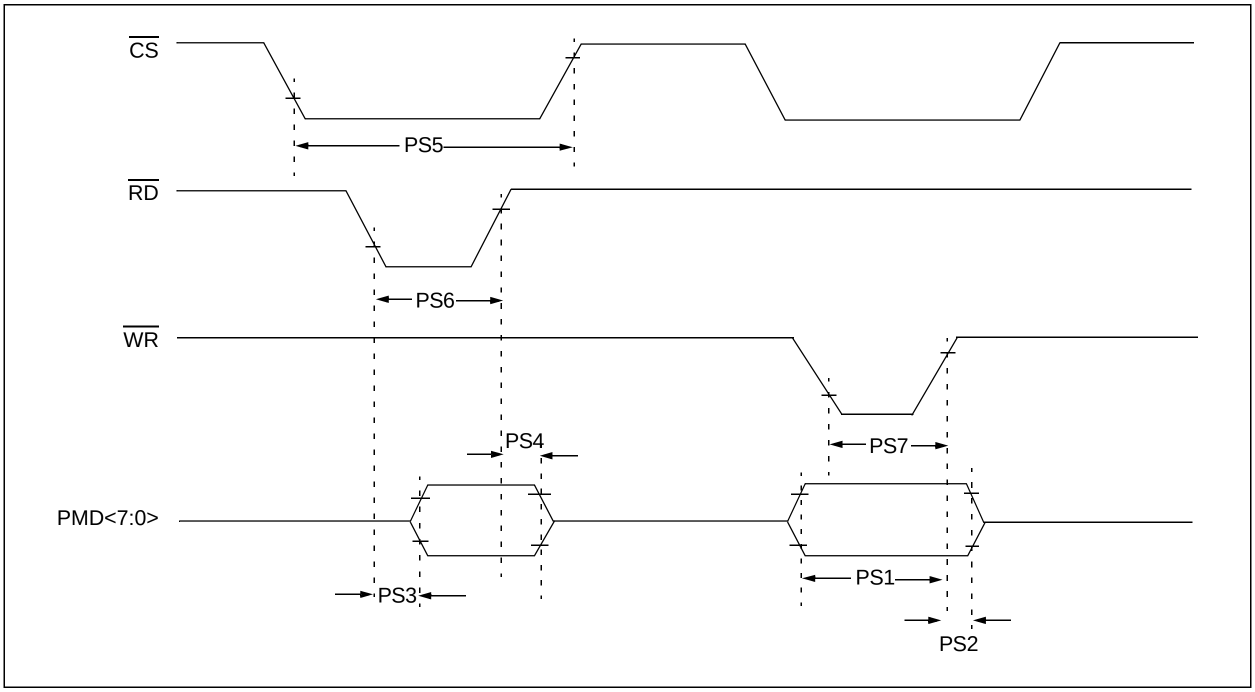


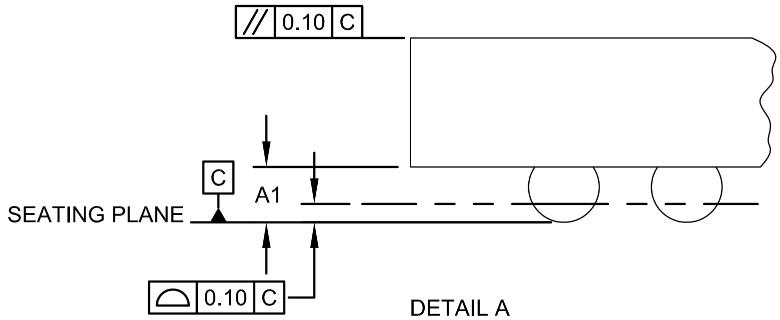
TABLE 29-37: PARALLEL SLAVE PORT REQUIREMENTS

AC CHARACTERISTICS			**Standard Operating Conditions: 2.3V to 3.6V** (unless otherwise stated) Operating temperature -40°C ≤ TA ≤ +85°C for Industrial -40°C ≤ TA ≤ +105°C for V-Temp				
Param. No.	**Symbol**	**Characteristics(1)**	**Min.**	**Typical**	**Max.**	**Units**	**Conditions**
PS1	TdtV2wrH	Data In Valid before $\overline{WR}$ or $\overline{CS}$ Inactive (setup time)	20	—	—	ns	—
PS2	TwrH2dtI	$\overline{WR}$ or $\overline{CS}$ Inactive to Data – In Invalid (hold time)	40	—	—	ns	—
PS3	TrdL2dtV	$\overline{RD}$ and $\overline{CS}$ Active to Data – Out Valid	—	—	60	ns	—
PS4	TrdH2dtI	$\overline{RD}$ Active or $\overline{CS}$ Inactive to Data – Out Invalid	0	—	10	ns	—
PS5	Tcs	$\overline{CS}$ Active Time	TPB + 40	—	—	ns	—
PS6	TWR	$\overline{WR}$ Active Time	TPB + 25	—	—	ns	—
PS7	TRD	$\overline{RD}$ Active Time	TPB + 25	—	—	ns	—

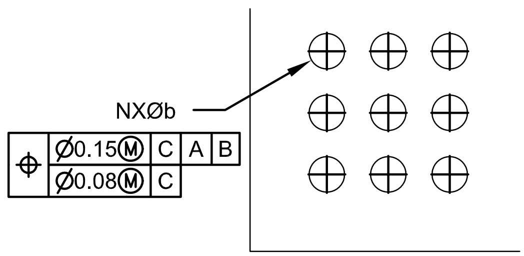
Note 1: These parameters are characterized, but not tested in manufacturing.

121-Lead Plastic Thin Profile Ball Grid Array (BG) - 10x10x1.10 mm Body [XBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



DETAIL A
(ROTATED 90° CW)



DETAIL B

	Units	MILLIMETERS		
	Dimension Limits	MIN	NOM	MAX
Number of Contacts	N		121	
Contact Pitch	e		0.80 BSC	
Overall Height	A	1.00	1.10	1.20
Standoff	A1	0.25	0.30	0.35
Molded Package Thickness	A2	0.55	0.60	0.65
Overall Width	E		10.00 BSC	
Array Width	E1		8.00 BSC	
Overall Length	D		10.00 BSC	
Array Length	D1		8.00 BSC	
Contact Diameter	b		0.40 TYP	

Notes:
1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Dimensioning and tolerancing per ASME Y14.5M.
   BSC: Basic Dimension. Theoretically exact value shown without tolerances.
   REF: Reference Dimension, usually without tolerance, for information purposes only.
3. The outer rows and colums of balls are located with respect to datums A and B.

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